



SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA

NOTE:

- Material:
    - Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
    - Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
  - Plating:
    - Contact terminal:
      - Contact area: Gold 1u" Min.
      - Solder area: Gold 0.8u" Min.
      - Underplating: Ni overall 500u" Min.
    - Cover:
      - Underplating: Ni overall 300u" Min.
      - Solder area: Gold 0.8u" Min.
  - Specification:
    - Current Rating: 0.5A max.
    - Contact Resistance: 50 mOhms max
    - Insulation Resistance: 1000 MOhms min./500VDC
    - Dielectric Withstanding Voltage: 500 V AC/1minute
    - Operating Temperature: -25°C to +85°C
    - Mating Cycles: 5000 Insertions
  - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
  - Part Must Comply Taisol HF WD-3-I-091 Specification.
  - Recommending A Metal More Than 0.15mm Thick.
- Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



深圳市华宇创精密电子有限公司

<b>TOLERANCE:</b> X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2' X.X' ±0.5'	<b>DRAWN BY :</b> 陈一鸣	<b>DATE :</b> 2014-02-23	<b>PART NAME:</b> NANO SIM 1.5H DIP TYPE卡托式
	<b>CHECKED BY:</b> 马跃	<b>DATE :</b> 2014-02-23	<b>PART NO.</b> HVCW313-SIM07-150B
<b>UNIT: mm [inch]</b> <b>SCALE: 1:1 SIZE: A4</b>	<b>APPROVED BY:</b> 邱敏	<b>DATE :</b> 2014-02-23	<b>DRAW NO:</b> HVC-2206021031
			<b>SHEET NO.</b> 1 OF 1